

What is claimed is:

1. A component of a film-forming device in which a thin film is formed on a substrate using a film-forming material, the component being characterized in that a large number of through holes each extending from the back face to the top face of the component are formed for the penetration of a cleaning solution into the boundary between the component and a film of the film-forming material adhered to the surface of the component and formed during the formation of the foregoing thin film.
2. The component of a film-forming device according to claim 1, wherein the through holes of the component is so designed that they have a diameter, which can inhibit the penetration of any particle of the film-forming material or the plasma thereof into the through holes.
3. The component of a film-forming device according to claim 1 or 2, wherein the through holes are formed in such a manner that they are not vertical to the surface of the component, but are tilted towards the horizontal direction.
4. The component of a film-forming device according to claim 1, wherein a layer consisting of a metal film easily soluble in the cleaning solution is formed on the surface of the component according to a method such as thermal spraying, vapor deposition, sputtering, plating and lamination techniques.
5. A method for cleaning a component of a film-forming device comprising the step of immersing, into a cleaning solution, a component as set forth in claim 1 for the removal of a film adhered to the component.
6. A method for cleaning a component of a film-forming device comprising the step of immersing, into a cleaning solution, a component as set forth in claim 2 for the removal of a film adhered to the component.
7. A method for cleaning a component of a film-forming device comprising the step of immersing, into a cleaning solution, a component as set forth in claim 3 for the removal of a film adhered to the component.
8. A method for cleaning a component of a film-forming device comprising the step of immersing, into a cleaning solution, a component as set forth in claim 4 for the removal of a film adhered to the component.